Texas Instruments introduces the latest development in high-power audio with the highest performing monolithic Class-D amplifier family in the market. With output power levels from 35 W to 650 W, support for high resolution audio and the lowest THD+N of any Class-D, the TPA32xx family can address your needs for powered speaker applications.

**Features**

**Active Crossover**
- Combine the TPA32xx with the TI DACs PCM5242 or PCM5252 to remove your passive crossover, reducing weight and system cost
- Shorten design time by using TI’s PurePath™ Studio tuning software

**Advanced Audio Processing**
- Improve your sound with TI’s audio algorithms
- Speaker equalization to tune the speaker frequency response using the integrated DSP
- Smart amps that maximize excursion without damaging the speaker

**High Efficiency**
- Highest output-power to idle-loss ratio in the market
- Boost your performance at lower output power levels with the use of Class-G

**Power Supplies**
- Reference designs that help you to get to production faster

For more information please visit: [ti.com/highpoweraudio](http://ti.com/highpoweraudio)
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